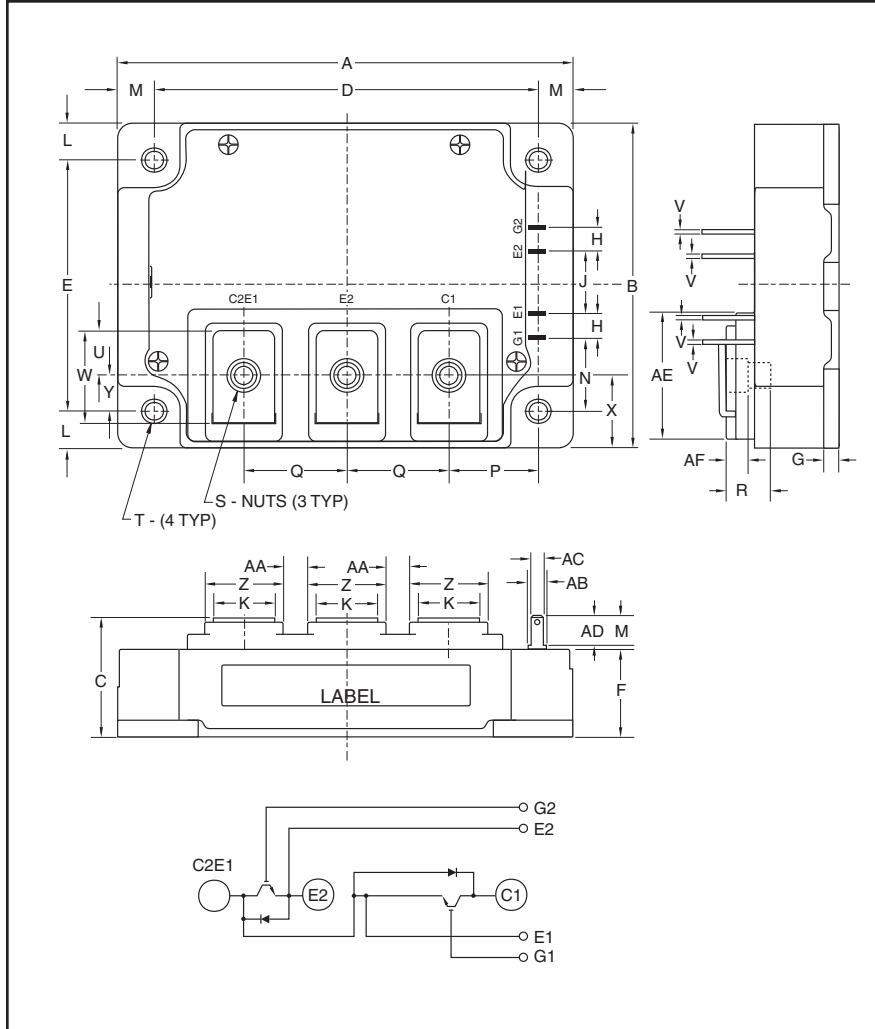


### Dual IGBTMOD™ NFJ-Series Module 400 Amperes/1200 Volts



Outline Drawing and Circuit Diagram

Dimensions	Inches	Millimeters
A	4.33	110.0
B	3.15	80.0
C	1.14+0.04/-0.01	29.0+1.0/-0.5
D	3.66±0.01	93.0±0.25
E	2.44±0.01	62.0±0.25
F	0.83	21.2
G	0.16	4.0
H	0.24	6.0
J	0.59	15.0
K	0.55	14.0
L	0.35	9.0
M	0.33	8.5
N	0.69	17.5
P	0.85	21.5
Q	0.98	25.0

Dimensions	Inches	Millimeters
R	0.47	12.0
S	M6 Metric	M6
T	0.26 Dia.	6.5 Dia.
U	0.4	10.0
V	0.02	0.5
W	0.87	22.2
X	0.72	18.25
Y	0.36	9.25
Z	0.71	18.0
AA	0.28	7.0
AB	0.16	4.0
AC	0.11	2.8
AD	0.3	7.5
AE	1.23	31.4
AF	0.21	5.3



#### Description:

Powerex IGBTMOD™ Modules are designed for use in high frequency applications; 30 kHz for hard switching applications and 60 to 70 kHz for soft switching applications. Each module consists of two IGBT Transistors in a half-bridge configuration with each transistor having a reverse-connected super-fast recovery free-wheel diode. All components and interconnects are isolated from the heat sinking baseplate, offering simplified system assembly and thermal management.

#### Features:

- Low ESW(off)
- Discrete Super-Fast Recovery Free-Wheel Diode
- Isolated Baseplate for Easy Heat Sinking

#### Applications:

- Power Supplies
- Induction Heating
- Welders

#### Ordering Information:

Example: Select the complete part module number you desire from the table below -i.e. CM400DU-24NFJ is a 1200V (V<sub>CEs</sub>), 400 Ampere Dual IGBTMOD™ Power Module.

Type	Current Rating Amperes	V <sub>CEs</sub> Volts (x 50)
CM	400	24

**CM400DU-24NFJ**  
**Dual IGBTMOD™ NFJ-Series Module**  
 400 Amperes/1200 Volts

**Maximum Ratings,  $T_j = 25^\circ\text{C}$  unless otherwise specified**

Characteristics	Symbol	Rating	Units
Collector-Emitter Voltage (G-E Short)	$V_{CES}$	1200	Volts
Gate-Emitter Voltage (C-E Short)	$V_{GES}$	$\pm 20$	Volts
Collector Current (Operation) <sup>*2</sup>	$I_C$	400	Amperes
Collector Current (Pulse) <sup>*2</sup>	$I_{CM}$	800	Amperes
Maximum Power Dissipation ( $T_C = 25^\circ\text{C}$ ) <sup>*2,*4</sup>	$P_C$	2450	Watts
Emitter Current (Operation) <sup>*2</sup>	$I_E^{*1}$	400	Amperes
Emitter Current (Pulse) <sup>*2</sup>	$I_{EM}^{*1}$	800	Amperes
Isolation Voltage (Charged Part to Baseplate, $f = 60$ Hz, AC 1 Minute)	$V_{ISO}$	2500	$V_{rms}$
Junction Temperature	$T_j$	-40 ~ +150	$^\circ\text{C}$
Storage Temperature	$T_{stg}$	-40 ~ +125	$^\circ\text{C}$

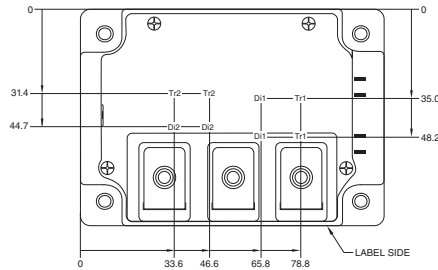
**Mechanical Characteristics**

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Torque Strength	M	Main Terminals, M6 Screw	31	35	40	in-lb
	M	Mounting, M6 Screw	31	35	40	in-lb
Weight			—	580	—	Grams

\*1 Represent ratings and characteristics of the anti-parallel, emitter-to-collector free wheeling diode (FWD).

\*2 Pulse width and repetition rate should be such that device junction temperature ( $T_j$ ) does not exceed  $T_{j(max)}$  rating.

\*4 Case temperature ( $T_C$ ) is measured point is just under the chips.



Each mark points to the center position of each chip.  
 Tr1 / Tr2: IGBT    D1 / D2: FWD. Tolerance  $\pm 1$  mm

**CM400DU-24NFJ**  
**Dual IGBTMOD™ NFJ-Series Module**  
 400 Amperes/1200 Volts

**Electrical Characteristics,  $T_j = 25^\circ\text{C}$  unless otherwise specified**

Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Collector-Cutoff Current	$I_{CES}$	$V_{CE} = V_{CES}, V_{GE} = 0V$	—	—	1.0	mA
Gate Leakage Current	$I_{GES}$	$\pm V_{GE} = V_{GES}, V_{CE} = 0V$	—	—	1.4	$\mu\text{A}$
Gate-Emitter Threshold Voltage	$V_{GE(th)}$	$I_C = 40\text{mA}, V_{CE} = 10V$	4.5	6.0	7.5	Volts
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C = 400A, V_{GE} = 15V, T_j = 25^\circ\text{C}^3$	—	5.0	6.5	Volts
		$I_C = 400A, V_{GE} = 15V, T_j = 125^\circ\text{C}^3$	—	5.0	—	Volts
Forward Transfer Admittance	$ y_{fs} $	$I_C = 400A, V_{CE} = 10V^3$	120	—	—	S
Input Capacitance	$C_{ies}$		—	—	63	nF
Output Capacitance	$C_{oes}$	$V_{CE} = 10V, V_{GE} = 0V$	—	—	5.3	nF
Reverse Transfer Capacitance	$C_{res}$		—	—	1.2	nF
Total Gate Charge	$Q_G$	$V_{CC} = 600V, I_C = 400A, V_{GE} = 15V$	—	1800	—	nC
Turn-on Delay Time	$t_{d(on)}$		—	—	300	ns
Turn-on Rise Time	$t_r$	$V_{CC} = 600V, I_C = 400A,$	—	—	100	ns
Turn-off Delay Time	$t_{d(off)}$	$V_{GE} = \pm 15V, R_G = 0.78\Omega,$	—	—	500	ns
Turn-off Fall Time	$t_f$	Inductive Load,	—	—	150	ns
Reverse Recovery Time	$t_{rr}^{*1}$	$I_E = 400A$	—	—	100	ns
Reverse Recovery Charge	$Q_{rr}^{*1}$		—	7.0	—	$\mu\text{C}$
Emitter-Collector Voltage	$V_{EC}^{*1}$	$I_E = 400A, V_{GE} = 0V^3$	—	5.5	7.0	Volts
Internal Gate Resistance	$R_{Gint}$	$T_C = 25^\circ\text{C}, \text{Per Switch}$	—	3.0	—	$\Omega$
External Gate Resistance	$R_G$		0.78	—	7.8	$\Omega$

**Thermal Resistance Characteristics,  $T_j = 25^\circ\text{C}$  unless otherwise specified**

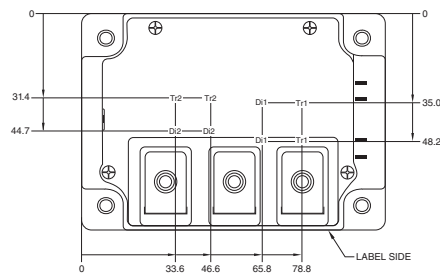
Characteristics	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal Resistance, Junction to Case	$R_{th(j-c)Q}$	Per IGBT Part <sup>*4</sup>	—	—	0.051	K/W
Thermal Resistance, Junction to Case	$R_{th(j-c)D}$	Per FWDi Part <sup>*4</sup>	—	—	0.093	K/W
Contact Thermal Resistance	$R_{th(c-f)}$	Case to Heatsink, Thermal Grease Applied <sup>*4*5</sup>	—	0.02	—	K/W

<sup>\*1</sup> Represent ratings and characteristics of the anti-parallel, emitter-to-collector free wheeling diode (FWDi).

<sup>\*3</sup> Pulse width and repetition rate should be such as to cause negligible temperature rise.

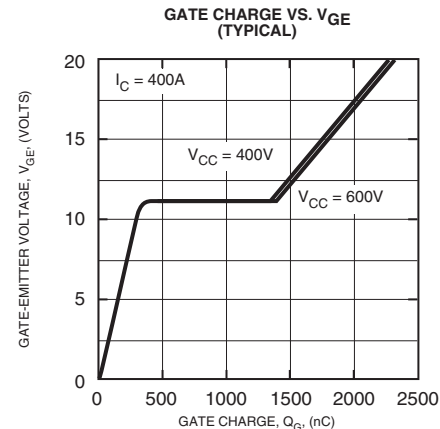
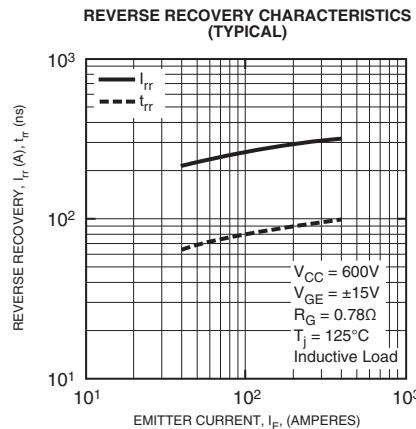
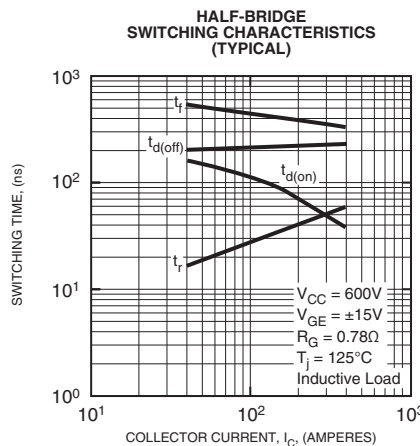
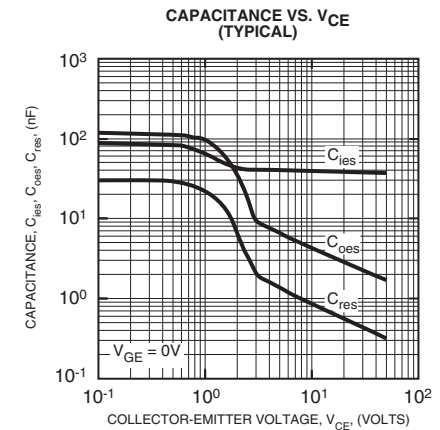
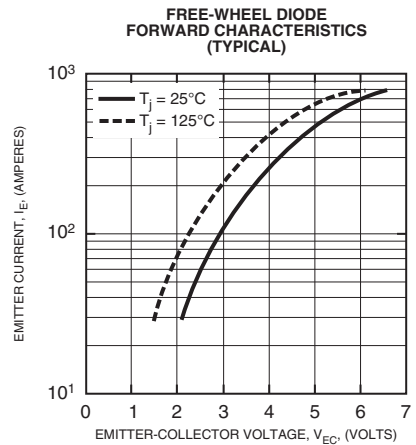
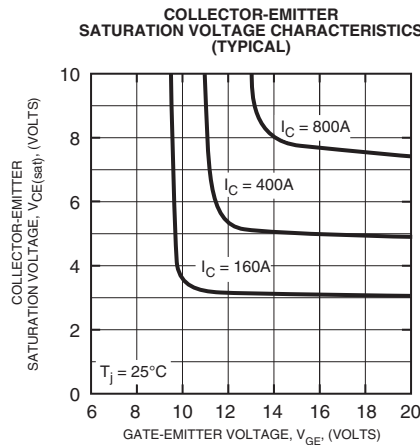
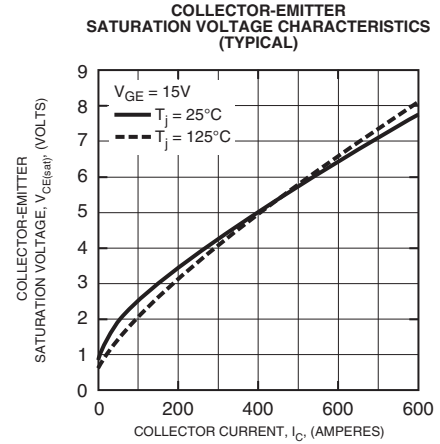
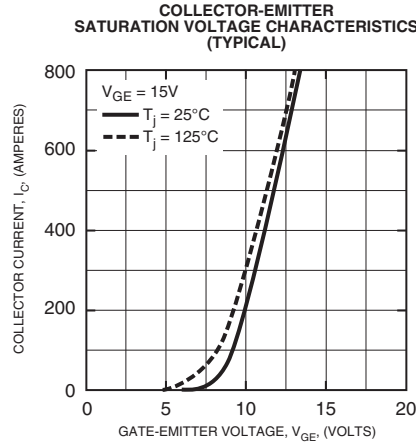
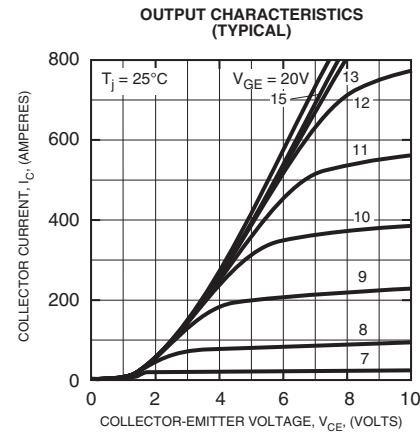
<sup>\*4</sup> Case temperature ( $T_C$ ) and heatsink temperature ( $T_f$ ) measured point is just under the chips.

If using this value, thermal resistance of heatsink,  $R_{th(f-a)}$ , should be measured just under the chips.



<sup>\*5</sup> Typical value is measured by using thermally conductive grease of  $\lambda = 0.9 \text{ [W/(m} \cdot \text{K)]}$ .

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